



# Process Change Notification

PCN Number: PCN-2019-126 Phase 1 CSP

PCN Notification Date: 09/29/2020

## Final PCN: Phase 1 for CSP components

Wafer Fabrication site transfers from Fab3E to Fab5 of Global Foundries in Singapore

Dear Customer,

We are pleased to announce the successful completion of wafer fabrication site transfer from Fab3E to Fab5 of Global Foundries in Singapore for the CSP (Chip Scale Package) components.

**\*Special Note:** Due to the global health and economic crisis, Cirrus Logic was required to change aspects of scheduling and amended the initial PCN into two phases.

Phase 1: CSP components

Phase 2: QFN components

**The Final PCN for QFN components will be submitted when the phase is completed.**

The described change is effective as of the successful completion of the Cirrus Logic qualification for this notification and delivery will commence immediately to ensure continuity of supply without disruption.

Cirrus Logic would like to take this opportunity to thank our customers for their cooperation and assistance in this respective matter. Any specific or immediate inquiries should be directed to your local Field Sales Representative.

If you have any questions, please contact your Sales Representative.

Sincerely,

Quality Systems Administrator  
Cirrus Logic Corporate Quality  
Phone: +1(512) 851-4000

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**Products Affected:**

The devices listed on subsequent pages are the complete list of affected devices. According to our records, one or more of these devices have been purchased by your organization within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

Technical details of this Process / Product Change follow on the next page(s).

<b>Title:</b>	Wafer Fabrication site transfers from Fab3E to Fab5 of Global Foundries in Singapore		
<b>Customer Contact:</b>	Local Field Sales Representative	<b>Phone:</b> (512) 851-4000	<b>Dept:</b> Corporate Quality
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Note 1	<b>Estimated Sample Availability Date:</b> Now	
<b>Change Type:</b>			
	Assembly Site	Assembly Process	Assembly Materials
X	Wafer Fab Site	Wafer Fab Process	Wafer Fab Materials
	Wafer Bump Site	Wafer Bump Process	Wafer Bump Material
	Test Site	Test Process	Design
	Electrical Specification	Mechanical Specification	Part Number
	Packing/Shipping/Labeling	X Other	
<b>Comments:</b>	"Other" – Device marking format and pin orientation <b>Note 1.</b> Now for the WM8994 device and all other devices in Q4 onwards		

## PCN Details

**Description of Change(s):**



- Fabrication site change from GF (Global Foundries) Fab3E to Fab5

**Phase 1: CSP components**

Affected Cirrus Logic Part Number
WM8962BECSN/R
WM8994ECS/R
WM8963ECSN/R
WM8958ECS/R



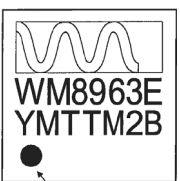

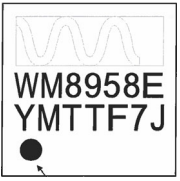

- Marking Format and Pin Orientation: Consistent with Cirrus Logic Mark Format Standard**

**Note:** Cirrus Logic acquired Wolfson in August 2014

Cirrus Logic Part Number	From	To	
WM8962BECSN/R			<b>TOP SIDE BRAND</b> Line 1: Part Number Line 2: Package Mark Line 3: Country of Origin

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Cirrus Logic Part Number	From	To	<b>PACKAGE MARK FIELDS</b> 12 character Package Mark appears on PO as 6 fields of 2 characters each in the following format: FFAARRLLYYWW                    where, FF = Foundry Code AA = Assembly Site Code RR = Die Rev Code LL = Lot Sequence Code YY = Year of Manufacture WW = Work Week of Manufacture
WM8994ECS/R			
WM8963ECSN/R			
WM8958ECS/R			

**Reason for Change:**

Global Foundries Fab3E site stopped production.

**Anticipated Impact on Form, Fit, Function, Quality or Reliability:**

No anticipated adverse impact to the Quality and/or Reliability of said product. However, the customer may have to adjust Pick-N-Place recognition system to adapt to the Cirrus Logic part marking and pin orientation standardization.

**Anticipated Impact on Material Declaration:**

No Impact to the Material Declaration                     Material Declarations or Product Content reports are driven from production data and will be available following the production release.

**Product Affected:**

**Phase 1: CSP components**

Affected Cirrus Logic Part Number
WM8962BECSN/R
WM8994ECS/R
WM8963ECSN/R
WM8958ECS/R

## Qualification Result

Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results			
Reliability Test	Standard	Conditions	Sample Size (PASS/FAIL)
<b>ESD-HBM</b> (Human Body Model ESD)	JS-001	JS-001	1 Lot @ 3 pcs ea. <b>Passed</b>
<b>ESD-CDM</b> (Charged Device Model ESD)	JS-002	JS-002	1 Lot @ 3 pcs ea. <b>Passed</b>
<b>LU</b> (Latch-Up)	JESD78	+ / - 100 mA, 1.5xVDDmax	1 Lot @ 3 pcs ea. <b>Passed</b>
<b>ELFR</b> (Early Life Failure Rate)	JESD22-A108	125°C / Dynamic Bias, 48hrs	1 Lot @ 1000 pcs ea. <b>Passed</b>
<b>HTOL</b> (High Temperature Operating Life)	JESD22-A108	125°C / Dynamic Bias, 1000hrs	1 Lot @ 77 pcs ea. <b>Passed</b>
<b>HTSL</b> (High Temperature Storage Life)	JESD22-A103	150°C, 1000 Hrs	3 Lots @ 77 pcs ea. <b>Passed</b>
<b>PC</b> (Precondition)	J-STD-020	Bake: 24Hr 125°C; MSL 3 192Hrs 30°C / 60% RH Soak, (Reflow 260°C x3)	3 Lots @ 77 pcs ea. <b>Passed</b>
<b>TC</b> (Temperature Cycling)	JESD22-A104	-40°C to +125°C for 1000 cycles (Post Precon)	3 Lots @ 77 pcs ea. <b>Passed</b>
<b>Notes:</b> <ul style="list-style-type: none"> <li>• Qualification tests “pass” on zero fails for each test.</li> <li>• The WM8958 component served as the primary qualification vehicle for silicon qualification and WM8962, WM8963, and WM8994 components are QBS.               <ul style="list-style-type: none"> <li>○ Test HBM, CDM, LU, ELFR, HTOL and HTSL items</li> </ul> </li> <li>• The WM8958 component served as the primary qualification vehicle for package qualification and WM8962, and WM8963 components are QBS.               <ul style="list-style-type: none"> <li>○ Test HTSL, PC, and TC items</li> </ul> </li> <li>• The WM8994 component served as a qualification vehicle for package qualification.               <ul style="list-style-type: none"> <li>○ Test HTSL, PC, and TC items</li> </ul> </li> <li>• Phase 1 components: WM8962B, WM8994, WM8963, and WM8958</li> </ul>			